

Title (en)
ELECTRONIC COMPONENT COMPRISING EXTERNAL SURFACE CONTACTS AND A METHOD FOR PRODUCING THE SAME

Title (de)
ELEKTRONISCHES BAUTEIL MIT USSEREN FL CHENKONTAKTEN UN D VERFAHREN ZU SEINER HERSTELLUNG

Title (fr)
COMPOSANT ELECTRONIQUE COMPRENANT DES CONTACTS DE SURFACE EXTERIEURS ET PROCEDE DE PRODUCTION DE CE COMPOSANT

Publication
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Application
EP 03755901 A 20030523

Priority

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- DE 10224124 A 20020529

Abstract (en)
[origin: WO03103042A2] The invention relates to an electronic component (1) and a method for producing the same. Said component comprises external surface contacts (2) and a rewiring structure (3), in addition to a semiconductor chip (4) comprising contact surfaces (5). The external surface contacts (2) are electrically connected to the contact surfaces (5) at least by means of the rewiring structure (3) and the external surface contacts (2) and/or the rewiring structure (3) comprise(s) metal that has been deposited in a chemically or galvanically selective manner.

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H01L 23/055; **H01L 25/10**

IPC 8 full level
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Citation (search report)
See references of WO 03103042A2

Citation (examination)

- US 5976912 A 19991102 - FUKUTOMI NAOKI [JP], et al
- JP 2001044589 A 20010216 - NITTO DENKO CORP

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DE

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WO 03103042 A2 20031211; **WO 03103042 A3 20040408**; DE 10224124 A1 20031218; EP 1508166 A2 20050223; US 2006091561 A1 20060504

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